

New Products: mAgic PE338

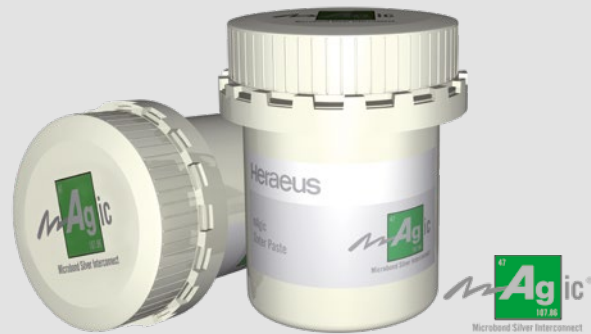
Ag Sinter Paste for Stencil Printing

mAgic Pressure Sinter Paste ASP338-28 is a lead-free die attach material with improved workability on copper surfaces.

mAgic Pressure Sinter Paste ASP338-28 F1510 is a patented high reliability material that increases life time performance with wide band gap material SiC and GaN.

ASP338-38 & ASP338-28 F1510 Benefits

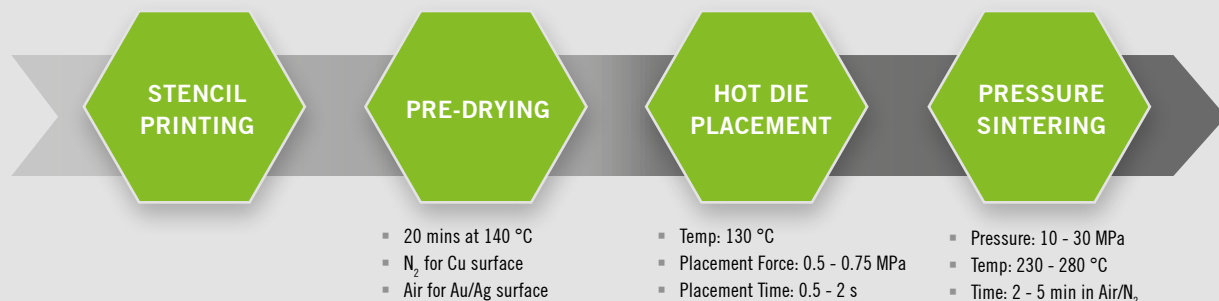
- Improves device reliability
- High thermal conductivity for longer lifetime
- High electrical conductivity improves device efficiency
- Enables high operating temperature
- Lead-free and halogen zero formulation for environmental compliance
- No flux residue, no cleaning required



Benchmarking (Lead Free Solder Paste vs. PE338 Ag Sinter Paste Series)

Series	Solder Paste SnAg3.5	mAgic Paste ASP338-28	mAgic Paste ASP338-28 F1510
Process Temperature (°C)	~ 250	> 230	
Electrical Resistivity (mΩ.cm)	0.02	≤ 0.010	
Thermal Conductivity (W/m.K)	57	> 150	
CTE (ppm/K)	27.9	19	15
E-Modulus (GPa)	33.4	40 - 65	25 - 40

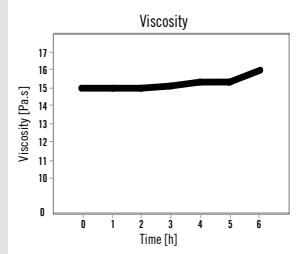
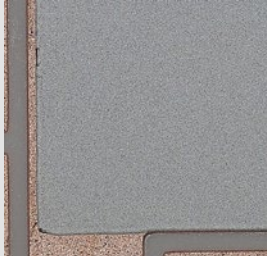
Pressure Sinter Paste Process and Application



* Varies depending on assembly

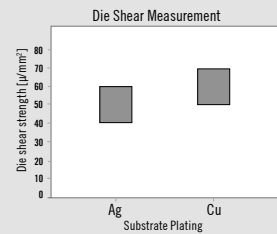
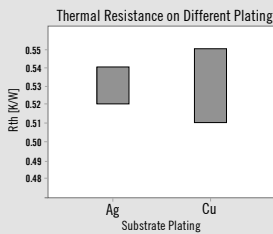
Product ID: ASP338-28 & ASP338-28 F1510

Printing Application Over Time

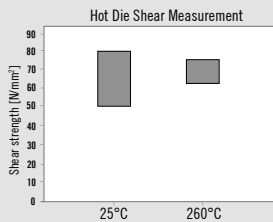


- Excellent printing performance overtime
- Consistent paste deposit volume for high production efficiency
- Stable rheology for long stencil life

Thermal Conductivity and Die Shear Strength Chart



- Die Size: 4x4 mm, Ag Die
- Pressure Applied: 230 °C, 10 MPa, 3 mins ; 20 MPa, for Cu



- Die Size: 10x10 mm, Ag Die, Cu Substrate
- Pressure Applied: 230 °C, 20 MPa, 5 mins

Reliability tests	Condition	Results
TCT (Temperature Cycle Test)	-65 °C / +150 °C	Passed
PCT (Pressure Cooker Test)	121 °C, 100 % RH, 2 atm	Passed
HTST (High Temperature Storage Test)	250 °C, 1000 hrs	Passed
Un-Biased HAST	130 °C/ 85 %, 96 hrs	Passed

Product Properties

Physical Properties	ASP338-28	ASP338-28 F1510
Alloy	Silver	
Metal content	82 %	73 %
Fillers	0 %	10 %
Particle size	≤ 20 µm	
Sinter temperature	≥ 230 °C	
Halogen content	Halogen Zero	
Compatible surfaces	Ag, Au, Cu	
Sinter atmosphere	Air, N ₂	

Application/Process

Printing	Yes
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Features & Benefits

Work life	8 hrs
Shelf life	6 mths
Residue cleaning	Not required
Storage condition	2 – 10 °C

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